

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1.-4. (Cancelled)

5. (Previously Presented) A semiconductor device, comprising:
a lower carrier substrate;
a plurality of upper carrier substrates mounted on the lower carrier substrate, each of the upper carrier substrates including a plurality of semiconductor chips stacked thereon; and
a protruding electrode group arranged on the lower carrier substrate, the protruding electrode group excluded from a region where a semiconductor chip is mounted on the lower carrier substrate so as to be arranged to be overlapped by ends of the upper carrier substrates.

6. (Previously Presented) A semiconductor device, comprising:
a lower carrier substrate;
a plurality of upper carrier substrates mounted on the lower carrier substrate, each of the upper carrier substrates including a plurality of semiconductor chips stacked thereon;
a semiconductor chip mounted on the lower carrier substrate;
a plurality of land electrodes formed on the lower carrier substrate; and

a protruding electrode arranged on a part of each of the plurality of land electrodes,

wherein the upper carrier substrates are supported by the protruding electrodes such that an end of each of the upper carrier substrates overlap the semiconductor chip mounted on the lower carrier substrate.

7. (Previously Presented) A semiconductor device, comprising:

a first carrier substrate;

a first semiconductor chip mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate; and

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode.

8. (Previously Presented) A semiconductor device, comprising:

a first carrier substrate;

a first semiconductor chip mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second semiconductor chip mounted on the second carrier substrate;

a region without a protruding electrode which is provided along at least a first side of the second carrier substrate; and

a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode.

9. (Cancelled)

10. (Cancelled)

11. (Previously Presented) An electronic device, comprising:

a first carrier substrate;

a first electronic component mounted on the first carrier substrate;

a rectangle-shaped second carrier substrate;

a second electronic component mounted on the second carrier substrate;

a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate; and

a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first electrode component under the region without a protruding electrode.

12. (Previously Presented) An electronic device, comprising:

- a first carrier substrate;
- a first electronic component mounted on the first carrier substrate;
- a rectangle-shaped second carrier substrate;
- a second electronic component mounted on the second carrier substrate;
- a region without a protruding electrode which is provided along at least a first side of the second carrier substrate; and
- a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first electronic component under the region without a protruding electrode.

13. (Previously Presented) Electronic equipment, comprising:

- a first carrier substrate;
- a first semiconductor chip mounted on the first carrier substrate;
- a rectangle-shaped second carrier substrate;
- a second semiconductor chip mounted on the second carrier substrate;
- a region without a protruding electrode that is provided along at least two sides which intersect at a first vertex of the second carrier substrate;
- a protruding electrode group which is provided along at least two sides which intersect at a second vertex of the second carrier substrate opposite the first vertex, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode; and
- a motherboard where the first carrier substrate is mounted.

14. (Previously Presented) Electronic equipment, comprising:

- a first carrier substrate;
- a first semiconductor chip mounted on the first carrier substrate;
- a rectangle-shaped second carrier substrate;
- a second semiconductor chip mounted on the second carrier substrate;
- a region without a protruding electrode which is provided along at least a first side of the second carrier substrate;
- a protruding electrode group which is provided along a second side of the second carrier substrate opposite the first side, and along at least a third side which intersects the second side, and which is bonded to the first carrier substrate so as to arrange the first semiconductor chip under the region without a protruding electrode; and
- a motherboard where the first carrier substrate is mounted.

15.-18. (Cancelled)